

## Dual Fixed and Floating Point C6670 Multicore DSP Processing Engine VPX-8320

PX-8320 Product

### Description

Powerful, high-performance fixed-point and floating-point DSP signal processing engine in an OpenVPX form factor (VITA 65).

#### **Key Features**

- Two TI guad-core TMS320C6670 DSPs
- Fixed and floating point up to 26.6 GMacs per core @ 1 GHz / 16 GFlops per core @ 1 GHz
- 1 GB of DDR3 SDRAM per DSP
- High-speed 40 Gbit TI Hyperlink interprocessor communications (between DSPs)
- VPX module supporting PCI Express x4 Gen 2 (VITA 42.3) (2 GB/s full-duplex)
- Front panel I/O: AIF (2 ports, 4 lanes each)\* and GigE\* (2 ports)
- VPX P2 High-speed serial I/O: SRIO\* (6 lanes), AIF\* (2 lanes) and SGMII\* (2 lanes)
- VPX P2 Single-ended I/O: GPIO (14 pins), RS-232
- C6670 is binary backwards compatible with C67xx, C64x and C62x

#### Sample Applications

- Satellite Communications (SATCOM) including satellite earth stations
- LTE/WiMAX development and test
- Industrial Control
- Signals Intelligence (SIGINT-COMINT/ELINT)
- Software Defined Radio (SDR)
- Cellular base station development and test
- High density DSP processing

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#### Features of the C6670 DSP

- Please refer to TI datasheets for full details: http:// www.ti.com/product/tms320c6670
  - 4 cores
  - Wireless coprocessor (Integrated Viterbi, Turbo, and FTT)
  - Antenna interface for OBSAI/CPRI

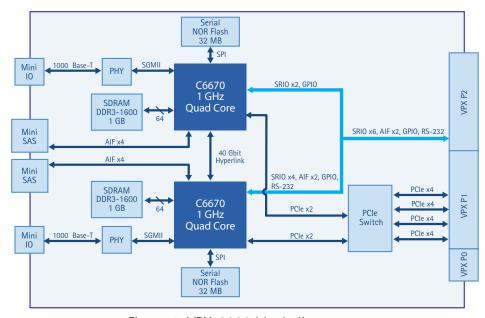


Figure 1. VPX-8320 block diagram

\*see "Future Options" section

#### **Specifications**

[ general ]	Processors	3U OpenVPX (VITA 65) Module Compatible with Slot Profiles MOD3-PAY-1D-16.2.6-1, MOD3-PAY-1D-16.2.6-2, MOD3-PAY-2F-16.2.7-1, and MOD3-PAY-2F-16.2.7-2 Two 1 GHz TMS320C6770 fixed-point and floating-point DSPs from Texas Instruments 1 GB of DDR3 SDRAM per DSP 1 GHz
[ external interfaces ]		From each DSP to PCle switch: PCle x2 Gen 2 From PCle switch to VPX P1 connector: 4 ports of PCle x4 Gen 2 (2 GB/s full duplex) (VITA 42.3) VPX P2 serial: SRIO* (6 lanes), AIF* (2 lanes), RS-232 VPX P2 single-ended GPIO: 30 (8 dedicated pins from each DSP, plus 14 pins factory configurable to connect to DSPs or PCle switch Front panel: AIF (2 ports Mini SAS connector, 4 lanes each) and GigE (2 ports Mini IO) Available for debug support via connector accessible on solder side of the board
[ onboard fabric ]	Between DSPs	
[ performance ]	Fixed point Floating point	2 DSPs per XMC module, 4 cores per DSP For more details, please refer to the TI C6670 datasheet up to 26.6 GMacs per core @ 1 GHz up to 16 GFlops per core @ 1 GHz
[ host requirements ]	Supported Host OS	RedHat Enterprise Linux 5.9 on INTEL i7 SBC GHS INTEGRITY 11.0.4 on CES RIOV-2473JE SBC
[ development software ]	quicComm	The quicComm software suite supports on both the host and target processors. quicComm provides functions for: • Configuration and control • Initiating PCle DMA data transfers It also provides a complete set of examples
[ other software ]	Debug Support	Support for TI's Code Composer Studio via JTAG emulator is provided (JTAG emulator sold separately)
[ electrical ]	Supply Voltage (DC) Power Estimate	+3V and +5V TBD
[ mechanical ]	Size	Standard VITA 46 VPX 3U (100mm(high) x 160mm(deep), 0.8 or 1.0 inch pitch)
[ environmental ] Operating Temperature range RoHS		0 to 50° C forced air 5 of 6 compliant
Interfaces		-40 to 70° C forced air 6 of 6 compliant Software support for AIF, GigE, SRIO Speed increase to 50 Gbps (when available on the C6670 DSP)

